SN54LS112A, SN54S112, SN74LS112A, SN74S112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR D2661, APRIL 1982-REVISED MARCH 1988

SDLS011

- Fully Buffered to Offer Maximum Isolation from External Disturbance
- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

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These devices contain two independent J-K negative-edge-triggered flip-flops. A low level at the preset and clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the J and K inputs meeting the setup time requirements are transferred to the outputs on the negative-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by tying J and K high.

The SN54LS112A and SN54S112 are characterized for operation over the full military temperature range of ~55°C to 125°C. The SN74LS112A and SN74S112A are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)

	IN	ουπ	PUTS			
PRE	<u>CLR</u>	CLK	J	К	a	ā
L	н	х	х	х	н	L
н	L	х	х	х	<u>ι</u>	н
L	L	x	х	х	н† –	H [†]
н	н	Ţ	L	L	<u>a</u> o	āο
н	н	ŧ	н	L	н	L
н	н	Ļ	L	н	L	н
н	н	Ţ	н	н	TOG	GLE
н	н	Н	_ x	х	ūο	āo

[†] The output levels in this configuration are not guaranteed to meet the minimum levels for V_{OH} if the lows at preset and clear are near V_{IL} minimum. Furthermore, this configuration is nonstable; that is, it will not persist when either preset or clear returns to its inactive (high) level.

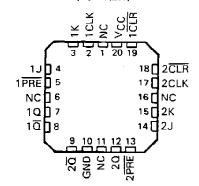
PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Taxas instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SN54LS112A, SN54S112 J OR W PACKAGE
SN74LS112A, SN74S112A D OR N PACKAGE
(TOP VIEW)

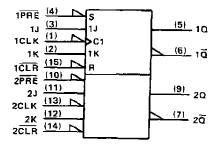
1CLK	1 2 3 4	U16 15 14 13	
10	5	12	2K
10	6	11	2J
20	7	10	2PRE
GND	8	9	2Q

SN54LS112A, SN54S112... FK PACKAGE (TOP VIEW)



NC-No internal connection

logic symbol[‡]



⁺This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

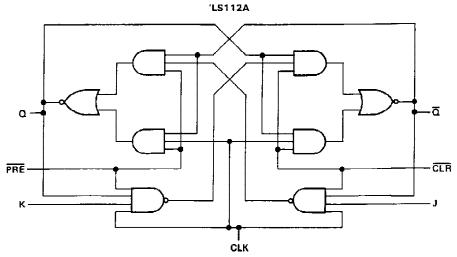
Pin numbers shown are for D, J, N, and W packages.

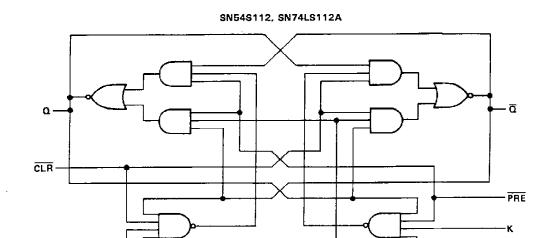
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SN54LS112A, SN54S112, SN74LS112A, SN74S112A DUAL J-K NEGATIVE EDGE TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

logic diagrams (positive logic)

.1

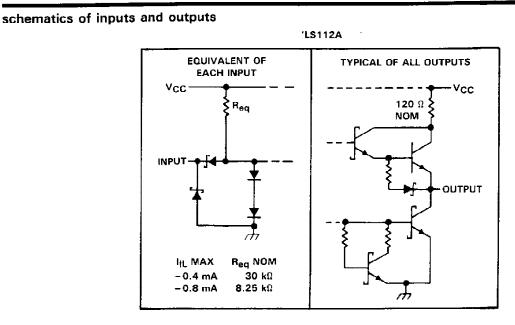




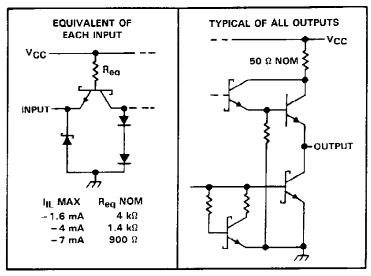
CLK



SN54LS112A, SN54S112, SN74LS112A, SN74S112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR



SN54S112, SN74S112A



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: 'LS112A	
SN54LS112, SN74LS112A	5.5 V
Operating free-air temperature range: SN54'	– 55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

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SN54LS112A, SN74LS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

recommended operating conditions

			SI	154LS11	2A	SN	74LS11	2A	LINUT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	v	
VIH	High-level input voltage		2			2			V	
VIL	Low-level input voltage				0.7			0.8	V	
юн	High-level output current				-0.4			-0.4	mΑ	
^I OL	Low-level output current			_	4			8	mΑ	
fclock	Clock frequency		O		30	0		30	MHz	
•	Pulse duration	CLK high	20			20				
t _w	Poise duration	PRE or CLR low	25			25			ns	
		Data high or low	20			20				
t _{su}	Set up time-before CLK1	CLR inactive	25			25			ns	
		PRE inactive	20			20				
th	Hold time-data after CLK1		0			0			Π\$	
TA	Operating free-air temperature		- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	ARAMETER	TEST	CONDITIONS		SM	154LS11	2A	ี รก	174LS11	2A	UNIT
P/	ANAIVIETER	TEST	CONDITIONS.		MIN	TYPI	MAX	MIN	TYPI	MAX	UNIT
VIK		$V_{CC} = MIN,$	$I_{1} = -18 \text{ mA}$		[-1.5			- 1.5	V
∨он		$V_{CC} = MIN,$ $I_{OH} = -0.4 \text{ mA}$	V _{IH} = 2 ∨,	V _{IL} ≠ MAX,	2.5	3.4		2.7	3.4		v
		$V_{CC} = MIN,$ IOL = 4 mA	$V_{1L} = MAX,$	V _{IH}		0.25	0.4		0.25	0.4	.,,
VOL		V _{CC} = MIN, I _{OL} = 8 mA	$V_{IL} = MAX,$	VIH = 2 V,					0.35	0.5	V
	J or K				[0.1			0.1	
4	CLR or PRE	$V_{CC} = MAX,$	VI = 7 V				0.3			0.3	mA
-	CLK	1					0.4			0.4	
	Jork						20			20	
нн	CLR or PRE	V _{CC} = MAX,	V = 2.7 V		-		60			60	μA
	CLK	1					80			80	
,	J or K	NA MAY	. <u>.</u>				-0.4			-0.4	4
ιL	All other	V _{CC} = MAX,	vi = 0.4 v				-0.8			-0.8	mA
los [§]		VCC = MAX,	see Note 2		- 20		- 100	- 20		- 100	mA
	otal)	$V_{CC} = MAX,$	see Note 3			4	6		4	6	mΑ

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. [‡] All typical values are at $V_{CC} = 5 V$, $T_A = 25 \,^{\circ}$ C.

[§]Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

NOTES: 2. For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V_O = 2.25 V and 2.125 V for the '54 family and the '74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

3. With all outputs open, ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.



SN54LS112A, SN74LS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

PARAMETER	FROM (INPUT)	то (OUTPUT)	TEST CONDITIONS	MIN	түр	мах	UNIT
fmax				30	45		MHz
^t PLH	CLR, PRE or CLK		$R_L = 2 k\Omega$, $C_L = 15 pF$		15	20	ាទ
^t PHL	CLA, FRE OF CLK				15	20	П\$

switching characteristics, $V_{CC} = 5 V$, $T_{\Delta} = 25 °C$ (see Note 4)

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

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SN54S112, SN74S112A DUAL J.K NEGATIVE EDGE TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

recommended operating conditions

			s	N54S1	2	SI	174511	2 A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			0.8	V
юн	High-level output current				- 1			- 1	mA
IOL .	Low-level output current				20			20	mΑ
		CLK high	6			6			
tw	Pulse duration	CLK low	6.5			6.5			пѕ
		PRE or CLR low	8			8			
t _{su}	Set up time-before CLK1	Data high or low	7			7			ns
th	Hold time-data after CLK↓		0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS [†]			5	SN54S1	12	SN74S112A			
		IESI	CONDITIONS		MIN	TYP [‡]	MAX	MIN	TYP‡	MAX	UNIT
VIK		$V_{CC} = MIN,$	lj = −18 mA				-1.2			-1.2	V
Voн		V _{CC} ≠ MIN, I _{OH} = −1 mA	V _{IH} = 2 V,	V _{IL} = MAX,	2.5	3.4		2.7	3.4		v
VOL		V _{CC} = MIN, IOL = 20 mA	V _{IH} = 2 V,	V _{IL} → 0.8 V,			0.5			0.5	۷
4		$V_{CC} = MAX.$	$V_1 = 5.5 V$				1			1	mA
	J or K	VCC = MAX	$y_{1} = 2.7 y_{1}$				50			50	μA
ήΗ	All other		vi = 2.7 v				100			100	μπ
	JorK						-1.6			- 1.6	
	CLR [§]			$V_{f} = 0.5 V$			- 7			-7	mΑ
μL	PRE	\neg VCC = MAX,	$v_{\rm f} = 0.5 v$				- 7			- 7	mμ
	CLK	1					-4			-4	
los¶		V _{CC} = MAX			-40		- 100	- 40		~ 100	mA
ICC #		V _{CC} = MAX.	see Note 3			15	25		15	25	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡]All typical values are at V_{CC} = 5 V, T_A = 25 °C.

Sclear is tested with preset high and preset is tested with clear high.

Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

#Values are average per flip-flop.

NOTE 3: With all outputs open, I_{CC} is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is grounded.



SN54S112, SN74S112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONI	MIN	Түр	МАХ	UNIT	
f _{max}					80	125		MHz
^t PLH	PRE or CLR	Q or Q				4	7	ns
to:	PRE or CLR (CLK high)	Q or Q	R ₁ = 280 Ω,	CL = 15 pF		5	7	
^t PHL	PRE or CLR (CLK low)		NL = 200 12, UL = 1		<u> </u>	5	7	ns
^t PLH	CLK	Q or Q	7			4	7	ns
^t PHL		abia				5	7	ns

switching characteristics, $V_{CC} = 5 V$, $T_A = 25 °C$ (see Note 4)

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

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26-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finisl	n MSL Peak Temp ⁽³⁾
JM38510/07102BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07102BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30103B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30103BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30103BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS112AJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54S112J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN74LS112AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS112ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS112ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS112ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS112AN	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS112AN3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74LS112ANE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS112ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS112ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S112AD	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74S112ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S112ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S112AN	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S112AN3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74S112ANE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S112ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S112ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS112AFK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS112AJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS112AW	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S112FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S112J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S112W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

PACKAGE OPTION ADDENDUM



LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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